Compliant with IEC 62474/ D9.00

Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: ASA 004 VFLGA 2.0x1.6x0.89mm Ni			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling e3
``	CAS Number	"Contained In" Sub-Component	% Total Weight			3.30	(mg) Total	Mold Compound	% ot Total Weight	
Basic Substance Silica(Amorphous) A	60676-86-0	Mold Compound	44.427	mg/part 2.488	ppm 444,270		Silica(Amorphous) A	60676-86-0	75.30	1
Silica(Amorphous) B	7631-86-9	Mold Compound	5.924	0.332	59,236		Silica(Amorphous) B	7631-86-9	10.04	1
Epoxy Resin	Trade Secret	Mold Compound	4.773	0.267	47,731		Epoxy Resin	Trade Secret	8.09	
Phenol Resin	9003-35-4	Mold Compound	1.776	0.099	17,759		Phenol Resin	9003-35-4	3.01	
Aluminium and its compounds	Trade Secret	Mold Compound	1.776	0.099	17,759		Aluminium and its compounds	Trade Secret	3.01	
Carbon Black	1333-86-4	Mold Compound	0.325	0.018	3,245		Carbon Black	1333-86-4	0.55	<u> </u>
Copper	7440-50-8	Lead Frame	7.018	0.393	70,185 41,837	1.09	(max) Tatal	Lead Frame	% of Total Weight	
Glass fibers Phenol, polymer	65997-17-3 9003-36-5	Lead Frame Lead Frame	4.184 4.184	0.234	41,837	1.09	(mg) Total Copper	7440-50-8	35.90	19.55
Silica, chemically prepared	7631-86-9	Lead Frame	1.564	0.234	15,640		Glass fibers	65997-17-3	21.40	-
Nickel	7440-02-0	Lead Frame	0.762	0.043	7,625		Phenol, polymer	9003-36-5	21.40	-
Barite	7727-43-7	Lead Frame	0.489	0.027	4.888		Silica, chemically prepared	7631-86-9	8.00	
Magnesium silicate	14807-96-6	Lead Frame	0.391	0.022	3,910		Nickel	7440-02-0	3.90	1
Araldite GY 250	25068-38-6	Lead Frame	0.391	0.022	3,910		Barite	7727-43-7	2.50	
(2-Methoxymethylethoxy)propanol	34590-94-8	Lead Frame	0.156	0.009	1,564		Magnesium silicate	14807-96-6	2.00	
Misc.	system	Lead Frame	0.293	0.016	2,933		Araldite GY 250	25068-38-6	2.00	
Aluminium-hydroxide-oxide	24623-77-6	Lead Frame	0.098	0.005	978		(2-Methoxymethylethoxy)propanol	34590-94-8	0.80	
Gold	7440-57-5	Lead Frame	0.020	0.001	196		Misc.	system	1.50	
Silver	7440-22-4	Die Attach 1	0.675	0.038	6,750		Aluminium-hydroxide-oxide	24623-77-6	0.50	
Epoxy Resin	Trade secret	Die Attach 1	0.075	0.004	750		Gold	7440-57-5	0.10	<u> </u>
SiO2 Filler	Trade Secret	Die Attach 2	0.772	0.043	7,723			Total	100.00	
Epoxy Resin	Trade Secret	Die Attach 2	0.390	0.022	3,899	0.04	(mg) Total	Die Attach 1	% of Total Weight	0.75
Acrylic Copolymer	Trade Secret	Die Attach 2	0.234	0.013	2,339		Silver Epoxy Resin	7440-22-4 Trade secret	90.00	
Phenol Resin	Trade Secret	Die Attach 2	0.234 3.810	0.013	2,339		Epoxy Resin	Total	10.00	1
Doped Silicon	7440-21-3	Chip (Die) 1		0.2.10	38,100					
Doped Silicon	7440-21-3	Chip (Die) 2	1.700 0.650	0.095	17,000	0.09	(mg) Total	Die Attach 2	% of Total Weight	1.63
Doped Gold	7440-57-5	Wire Bond 1		0.036	6,500		SiO2 Filler	Trade Secret	47.38	
Doped Gold	7440-57-5	Wire Bond 2	0.150 12.250	0.008	1,500		Epoxy Resin	Trade Secret	23.92	
Copper	7440-50-8 7440-02-0	Plating on external leads (pins) Plating on external leads (pins)			122,496		Acrylic Copolymer	Trade Secret	14.35	
Ni Au			0.383	0.021	3,828		Phenol Resin	Trade Secret	14.35	1
Ni Au	7440-02-0	Plating on external leads (pins)	0.128	0.007	1,276	0.21		Total	100.00	
Au	7440-57-5 0.0056	Plating on external leads (pins) TOTALS g Total Mass	0.128 : 100.000	0.007 5.600	1,276 1,000,000	0.21	Total (mg) Doped Silicon	Total Chip (Die) 1 7440-21-3	100.00 % of Total Weight 100.00	3.81
	7440-57-5 0.0056 EU Directives: 2 out exemption (2	Plating on external leads (pins) TOTALS g Total Mass 002/95/EC (27 January 2003) & Directive 2011/65/EU (08 ero)	0.128 : 100.000	0.007 5.600	1,276 1,000,000	0.21	Total (mg)	Total Chip (Die) 1	100.00 % of Total Weight	3.81
Au semiconductor device and its homogenous materials comply with and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) with diance with the above EU Directives has been verified via international substance is absent from the list above, the chemical subsorated's knowledge and belief as of the date of this document, t	7440-57-5 0.0056 EU Directives: 2 out exemption (2 design controls estance is NOT an	Plating on external leads (pins) TOTALS g Total Mass 002/95/EC (27 January 2003) & Directive 2011/65/EU (08 ero) supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and the reason to believe that the unavoidable impurity concer	0.128 : 100.000 June 2011) and to the best of M	0.007 5.600 2015/863/EU (1,276 1,000,000 31 March		Total (mg) Doped Silicon	Total Chip (Die) 1 7440-21-3 Total	100.00 % of Total Weight 100.00 100.00	3.81
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Au semiconductor device and its homogenous materials comply witt and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) with pliance with the above EU Directives has been verified via interna hemical substance is absent from the list above, the chemical sub rporated's knowledge and belief as of the date of this document, t t below the threshold of regulatory concern for any regulatory scl ing compounds used by Microchip meet the UL94 V0 flammability, full.com/global/eng/pages/offerings/industries/chemicals/plastics/ protective "tubes" in which the specific product is shipped are may	7440-57-5 0.0056 EU Directives: 2 out exemption (a design controls estance is NOT an ere is no credib eeme world-wide. estandard for pla	Plating on external leads (pins) TOTALS g Total Mass 002/95/EC (27 January 2003) & Directive 2011/65/EU (08 pero) supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and the reason to believe that the unavoidable impurity concestics. You can access the UL iQTM family of databases to	0.128 : 100.000 June 2011) and to the best of M tration of the ch	0.007 5.600 2015/863/EU (icrochip Tech emical substa	1,276 1,000,000 31 March nology		Total (mg) Doped Silicon Total (mg)	Total Chip (Die) 1 7440-21-3 Total Chip (Die) 2 7440-21-3	100.00 % of Total Weight 100.00 100.00 % of Total Weight 100.00	3.81
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